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(71) Applicant: **GLOBALWAFERS CO., LTD.** [CN/CN];
No. 8 Industrial East Road 2, Science-Based Industrial Park,
Hsinchu (TW).

(72) Inventor; and

(71) Applicant: **PARK, ShinBae** [KR/US]; 501 Pearl Drive, St.
Peters, Missouri 63376 (US).

(72) Inventor: **KIM, SangJun**; 501 Pearl Drive, St. Louis, Mis-
souri 63376 (US).

(74) Agent: **MUNSELL, Michael G.** et al.; Armstrong Teasdale
LLP, 7700 Forsyth Blvd., Suite 1800, St. Louis, Missouri
63105 (US).

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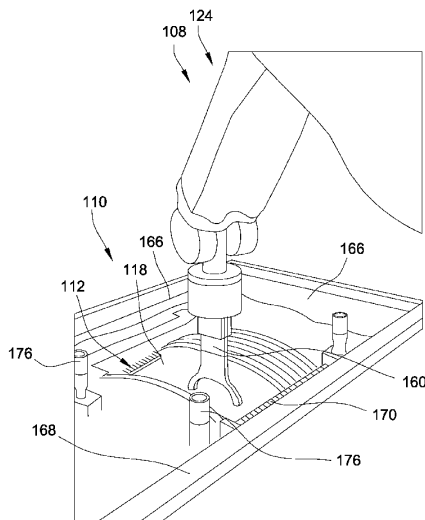


FIG. 7

(57) Abstract: A semiconductor wafer processing system for processing a set of semiconductor wafers includes a controller, a transfer robot controlled by the controller, a wet bath for containing a cleaning solution, and a cassette positioned in the wet bath for holding the set of wafers. The transfer robot transfers the wafer from a transfer location to the cassette and the controller controls the transfer robot during the transfer.

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